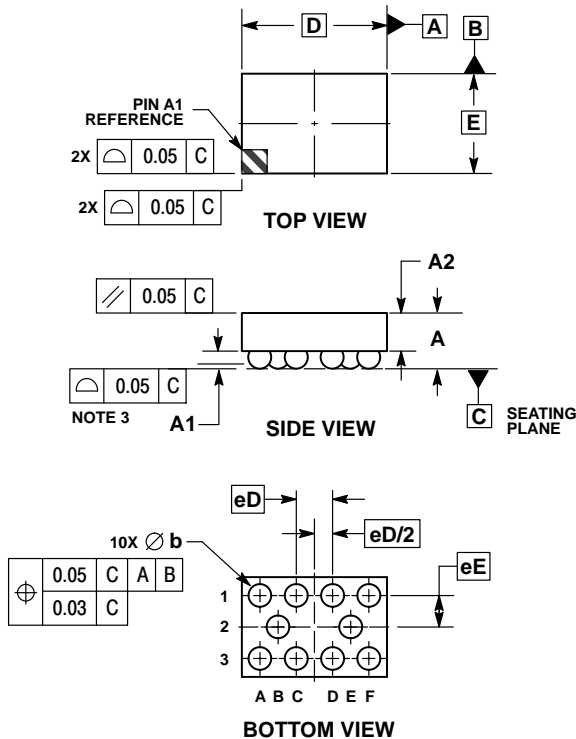




SCALE 4:1

WLCSP10, 1.60x1.10
CASE 567DE
ISSUE O

DATE 10 MAY 2011



NOTES:

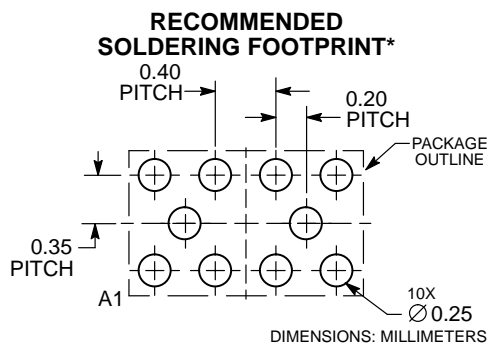
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.57	0.63
A1	0.17	0.24
A2	0.41	REF
b	0.24	0.29
D	1.60	BSC
E	1.10	BSC
eD	0.400	BSC
eE	0.347	BSC

GENERIC MARKING DIAGRAM*


- Y = Year
W = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP10, 1.60X1.10	PAGE 1 OF 1

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